Title: TE0820 - MIO Banks

A4 Number: TE0820 3BE21FL

Rev. 03

Date: 2018-03-29

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Filename: B_MIO.SchDoc
CHANGES REV01 to REV02

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1) Added MAC EEPROM (slave address:)
2) LIB components update
3) Fixed SD Card connection
4) Fixed sense connection from DCDC
5) Made correct power connection for VCU (removed DCDC, added resistors and caps like as Xilinx recommended)
6) Added resistors for variants (ZU+ with/without VCU)
7) Added termination resistors (240R) to VRP pins for all HP-banks

CHANGES REV02 to REV03

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1) Fixed VCU connection: add additional DCDC (0.9V)
2) LIB components update
3) Change package 1K resistors (0402 -> 0201)
4) Added LEDs (1x user LED, 1x LED for ERR.STATUS, 1xLED for ERR_OUT)
5) Change obsolete 2xSPI Flash (256MBit) -> 2xSPI Flash (512MBit)
6) Added additional DCDCs (PL_VCCINT_IO, PS_FP0V85)
7) Changed DCDC (U5) 6A (optional 4A)